



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-05-13
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV324LIPT	HD6R*V804BLL	A	BO2A	2013-05-13
Amount		UoM	Unit type	ST ECOPACK Grade
54.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	5 - 4.4 - 0.9	14	J bend	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HD6R*V804BLL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.986	mg	supplier	die	Silicon (Si)	7440-21-3		0.946	mg	959432	16893
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	9128	161
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1014	18
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1014	18
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	2028	96
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.02	mg	20284	357
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.005	mg	5071	89
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2028	96
Leadframe	Copper & its alloys	23.983	mg	supplier	alloy	Copper (Cu)	7440-50-8		23.937	mg	998082	427446
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.011	mg	459	196
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.02	mg	834	357
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.014	mg	584	250
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	42	18
Die attach	Other Organic Materials	0.347	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.263	mg	757925	4696
Die attach				supplier	glue or tape	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.035	mg	100865	625
Die attach				supplier	glue or tape	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.014	mg	40346	250
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	CE 417-470-1		0.021	mg	60519	375
Die attach				supplier	glue or tape	Polyoxypropylenediamine	9046-10-0		0.014	mg	40346	250
Bonding wire	Other inorganic materials	0.323	mg	supplier	wire	Gold (Au)	7440-57-5		0.323	mg	1000000	5768
encapsulation	Other Organic Materials	28.361	mg	supplier	mold compound	Silica, vitreous	60676-86-0		25.156	mg	886993	449214
encapsulation				supplier	mold compound	epoxy resin	Proprietary		2.269	mg	80004	40518
encapsulation				supplier	mold compound	Phenol resin	Proprietary		0.851	mg	30006	15196
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.085	mg	2997	1518